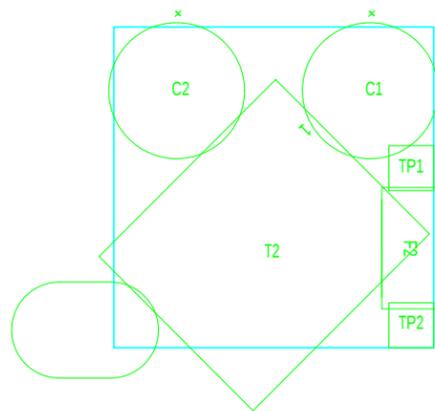


TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP8363_PRI	Rev.	C	L1									
Date:	{Start Date}	Filename:	{PCB Filename}	Engineer:	{Name}	PCB Dsgnr:	{Name}	Modified Date:	{Modification Date}	Software	PADs v9.2		



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP8363_PRI	Rev.	C									
Date:	{Start Date}	Filename:	{PCB Filename}	Engineer:	{Name}	PCB Dsgnr:	{Name}	Modified Date:	{Modification Date}	Software:	PADs v9.2	



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP8363_PRI	Rev.	C	L1						TA		
Date: {Start Date}	Filename: {PCB Filename}	Engineer: {Name}	PCB Dsgnr: {Name}	Modified Date: {Modification Date}					Software	PADs v9.2		

PLEASE NOTICE BOARD THICKNESS →

FABRICATION CHART			
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
<input checked="" type="checkbox"/> 0.005	<input checked="" type="checkbox"/> LAYER 1	<input checked="" type="checkbox"/> LAYER 1	<input type="checkbox"/> 1 OZ.
<input type="checkbox"/> 0.002	<input type="checkbox"/> LAYER 2	<input type="checkbox"/> LAYER 2	<input checked="" type="checkbox"/> 2 OZ.
<input type="checkbox"/> 0.003	<input type="checkbox"/> NONE	<input type="checkbox"/> NONE	<input type="checkbox"/> OTHER _____
<input type="checkbox"/> 0.125			
DESIGN	TRACE/GAP SPACING	LAYER COUNT	
<input type="checkbox"/> SMD	<input checked="" type="checkbox"/> 0.010/0.010	<input type="checkbox"/> SINGLE SIDED	
<input type="checkbox"/> THROUGH	<input type="checkbox"/> 0.006/0.007	<input checked="" type="checkbox"/> 2 LAYER	
<input checked="" type="checkbox"/> MIX	<input type="checkbox"/> 0.006/0.006	<input type="checkbox"/> 4 LAYER	
		<input type="checkbox"/> OTHER _____	

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD, SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEAR TYPE FR-4 OR COMPLIANT WITH LEAD FREE PROCESS.
- BASE LAMINATE:** EQUIVALENT, W/Tg +140 Deg C OR HIGHER, MINIMUM DECOMPOSITION TEMP (Td) OF 300 Deg c. CLASS EPOXY RESIN, COPPER CLAD IN ACCORDANCE WITH 1 LAYER STACKUP.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMD) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-D2485, COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND/OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
- TOLERANCES:** UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014 MIN. THK. MIN. THICK COPPER.
- FINISH:** PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TN OR SnAgCu, WITH RMA FLUX, 0.0007" TO 0.002" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK), LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Customer Order Details		Quantity	Unit Price	Total Price	Part Number	Part Name
Order No.	Rev.	Qty.	Unit Price	Total Price	Part Number	Part Name	Part Name	Part Name
123456789	1.0	1000	0.10	100.00	123456789	123456789	123456789	123456789

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